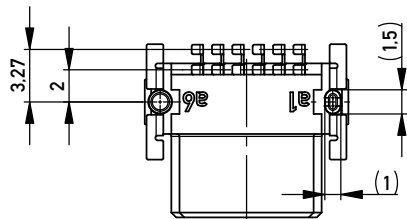
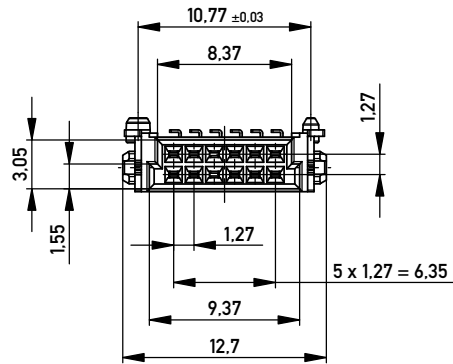
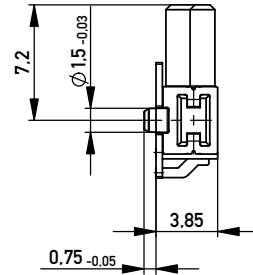
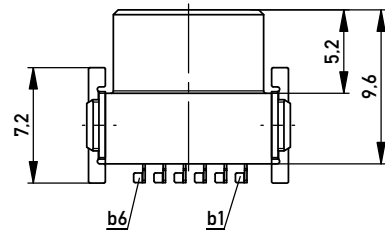
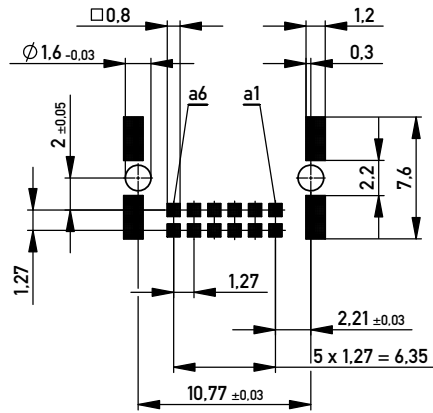
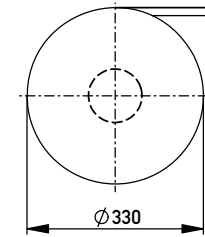


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 560 Stück
Packaging unit: 560 pcs

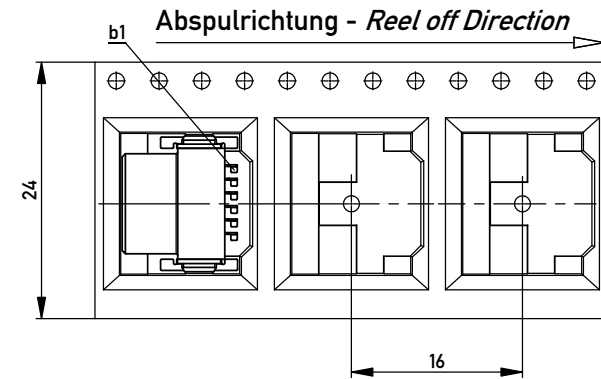


Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm



BA7-03 - Standard Bauhöhe

type7-03 - standard assembly height

Information:		Tolerances	All Dimensions in mm	Scale	3:1
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		www.ERNI.com		Federl. SMC-Q 12-SMD-BA7-03 Female SMC-Q 12-SMD-type7-03	
f	22.04.2014			154740	
Index	Date			I A3	
				Class	SMCQ

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